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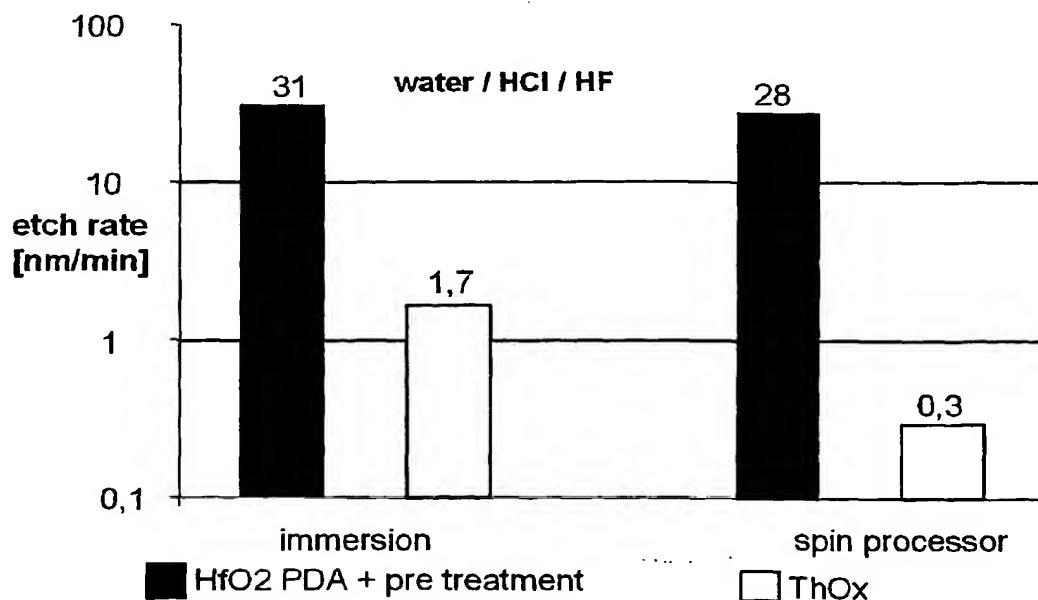
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*[Continued on next page]*

(54) Title: METHOD FOR SELECTIVE ETTCHING



(57) Abstract: Disclosed is a method of selective etching a first material on a substrate with a high selectivity towards a second material by flowing a liquid etchant across a substrate surface at a flow sufficient fast to generate a minimum mean velocity  $v$  parallel to the substrate's surface.

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